CRMCGH1003B

N-Channel 100V, 3.8mΩ Typ. Power MOSFET

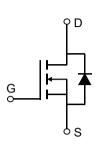
Description

Features

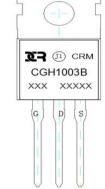
• 100V, 150A

 $R_{DS(ON)}$ Typ = 3.8m Ω @ V_{GS} = 10V

- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!



Schematic Diagram



Marking and Pin Assignment

Application

- Load Switch
- PWM Application
- Power Management

Package Marking and Ordering Information

Device	Marking	Package	Outline	TUBE(pcs)	Inner Box (pcs)	Per Carton (pcs)
CRMCGH1003B	CRMCGH1003B	TO-220C-3L	TUBE	50	2000	8000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		100	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	150	Α
I _D	Continuous Diam Current	T _C = 100°C	90	Α
I _{DM}	Pulsed Drain Current (1)		600	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		400	mJ
P_{D}	Power Dissipation	T _C = 25°C	189	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		0.66	°C/W
T_J,T_STG	Junction & Storage Temperature Range		-55 to 150	°C

CRMCGH1003B

N-Channel 100V, $3.8m\Omega$ Typ. Power MOSFET

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Cumple of	Danamatan	Conditions	, NA:	T	Mass	l limit
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0V$	100	-	-	V
$I_{\rm DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1.0	μΑ
$I_{\rm GSS}$	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.4	3	3.6	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10V, I_D = 30A$	-	3.8	5	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		- /	2767	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 50V,$ f = 1MHz	-	1383	-	pF
C_{rss}	Reverse Transfer Capacitance	I = IMHZ	X -	23	-	pF
Q_g	Total Gate Charge		-	74	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$	U .	28	-	nC
Q_gd	Gate Drain("Miller") Charge	$V_{DS} = 50V, I_{D} = 30A$	-	20	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	16	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	35	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 30A$, $R_{GEN} = 3\Omega$	-	50	-	ns
t _f	Turn-Off Fall Time		-	30	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
I _s	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	150	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	600	Α
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	31	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 15A$, di/dt = 100A/us	_	48	_	nC
	, , , , , , , , , , , , , , , , , , ,			-		

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =30V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =40A

^{3.} Pulse Test: Pulse Width $\!\!\leqslant\! 300\mu s,$ Duty Cycle $\!\!\leqslant\! 0.5\%.$

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Test Circuit

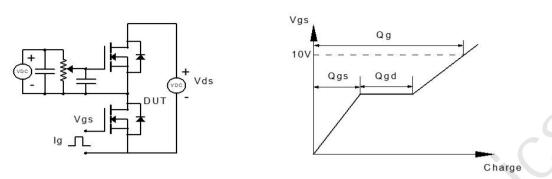


Figure 1: Gate Charge Test Circuit & Waveform

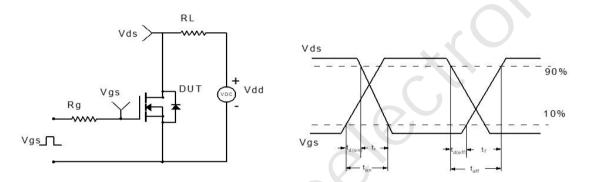


Figure 2: Resistive Switching Test Circuit & Waveform

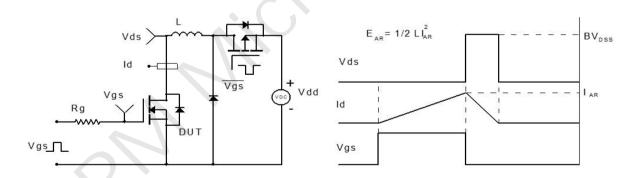


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

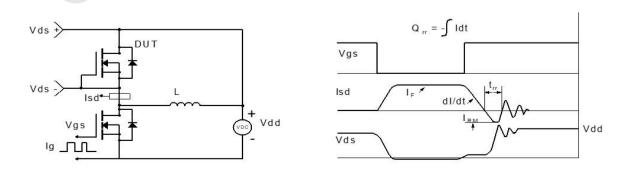
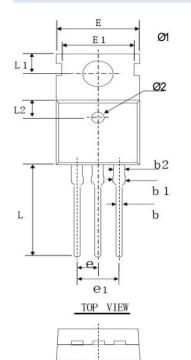


Figure 4: Diode Recovery Test Circuit & Waveform

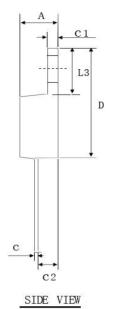
CRMCGH1003B

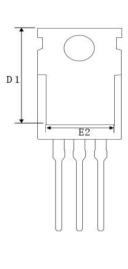
N-Channel 100V, 3.8mΩ Typ. Power MOSFET

Package Mechanical Data(TO-220C-3L)



SIDE VIBV





BOTTOM VIEW

SYMBOL	MIN	NOM	MAX	
A	4.30	4.50	4.70	
b	0.70	0.80	0.90	
b 1			1.42	
b 2	1.17	1.27	1.37	
С	0.40	0.50	0.60	
C 1	1.25	1.30	1.35	
C 2	2. 20	2.40	2.60	
D	15. 45	15.65	15.85	
D 1	13. 20	13.40	13.60	
E	9.80	10.0	10.2	
E 1	8.60	8.70	8.80	
E2	7.80	8.00	8.20	
e1	4.88	5.08	5.28	
L	12.95	13. 15	13.35	
L 1	2.70	2.80	2.90	
L2	2.40	2.50	2.60	
L3	6.30	6.50	6.70	
Ø1	3.50	3.60	3.70	
Ø2	1.35	1.50	1.65	
е	2.54BSC			

COMMON DIMENSIONS

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